LM2725/LM2726 **High Speed Synchronous MOSFET Drivers**

General Description

The LM2725/LM2726 is a family of dual MOSFET drivers that can drive both the top MOSFET and bottom MOSFET in a push-pull structure simultaneously. It takes a logic level PWM input and splits it into two complimentary signals with a typical 20ns dead time in between. The built-in shoot-through protection circuitry prevents the top and bottom FETs from turning on simultaneously. With a bias voltage of 5V, the peak sourcing and sinking current for each driver of the LM2725 is about 1.2A and that of the LM2726 is about 3A. In an SO-8 package, each driver is able to handle average current. (Under-Voltage-Lock-Out) ensures that all the driver outputs stay low until the supply rail exceeds the power-on threshold during system power on, or after the supply rail drops below power-on threshold by a specified hysteresis during system power down. The cross-conduction protection circuitry detects both the driver outputs and will not turn on a driver until the other driver output is low. The top gate bias voltage

needed by the top MOSFET can be obtained through an external bootstrap structure. Minimum pulse width is as low as 55ns.

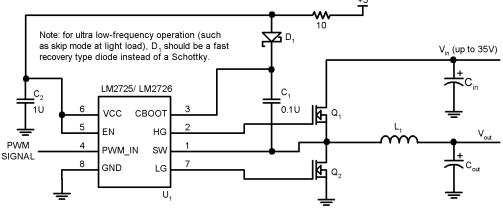
Features

- High peak output current
- Adaptive shoot-through protection
- 36V SW pin absolute maximum voltage
- Input Under-Voltage-Lock-Out
- Typical 20ns internal delay
- Plastic 8-pin SO package

Applications

- High Current DC/DC Power Supplies
- High Input Voltage Switching Regulators
- Microprocessors

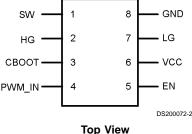
Typical Application



DS200072-1

Connection Diagram

8-Lead Small Outline Package



© 2000 National Semiconductor Corporation

DS200072

www.national.com

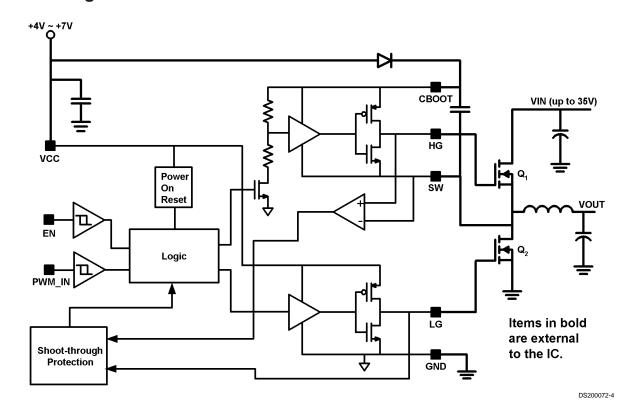
Ordering Information

Order Number	Package Type	NSC Package Drawing	Supplied As
LM2725	LM2725M		95 Units/Rail
	LM2725MX	M08A	2500 Units/Reel
LM2726	LM2726M	IVIUOA	95 Units/Rail
	LM2726MX		2500 Units/Reel

Pin Description

Pin	Name	Function
1	SW	Top driver return. Should be connected to the common node of top and bottom FETs
2	HG	Top gate drive output
3	СВООТ	Bootstrap. Accepts a bootstrap voltage for powering the high-side driver
4	PWM_IN	Accepts a 5V-logic control signal
5	EN	Chip Enable
6	VCC	Connect to +5V supply
7	LG	Bottom gate drive output
8	GND	Ground

Block Diagram



Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

 VCC
 7.5V

 CBOOT
 42V

 CBOOT to SW
 8V

 SW to PGND
 36V

 Junction Temperature
 +150°C

Power Dissipation

(Note 2) 720mW

Storage Temperature -65° to 150°C

ESD Susceptibility

Human Body Model (Note 3) 1 kV Soldering Time, Temperature 10sec., 300°C

Operating Ratings (Note 1)

VCC 4V to 7V Junction Temperature Range 0° to 125°C

Electrical Characteristics LM2725

VCC = CBOOT = 5V, SW = GND = 0V, unless otherwise specified. Typicals and limits appearing in plain type apply for $T_A = T_J = +25^{\circ}C$. Limits appearing in **boldface** type apply over the entire operating temperature range.

Symbol	Parameter	Condition	Min	Тур	Max	Units
POWER SUPI	PLY					1
l _{q_op}	Operating Quiescent Current	PWM_IN = 0V		180	250	μА
I _{q_sd}	Shutdown Quiescent Current	EN = 0V, PWM_IN = 0V		0.5	15	μΑ
TOP DRIVER						•
	Peak Pull-Up Current	Test Circuit 1, $V_{bias} = 5V$, $R = 0.1\Omega$		1.2		А
	Pull-Up Rds_on	$I_{CBOOT} = I_{HG} = 0.7A$		2.4		Ω
	Peak Pull-down Current	Test Circuit 2, $V_{bias} = 5V$, $R = 0.1\Omega$		-1.0		А
	Pull-down Rds_on	$I_{SW} = I_{HG} = 0.7A$		1.4		Ω
t ₄	Rise Time	Timing Diagram, C _{LOAD} =		17		ns
t ₆	Fall Time	3.3nF		10		ns
t ₃	Pull-Up Dead Time	Timing Diagram		23		ns
t ₅	Pull-Down Delay	Timing Diagram, from PWM_IN Falling Edge		21		ns
BOTTOM DRI	VER					
	Peak Pull-Up Current	Test Circuit 3, $V_{bias} = 5V$, $R = 0.1\Omega$		1.2		А
	Pull-up Rds_on	$I_{VCC} = I_{LG} = 0.7A$		2.6		Ω
	Peak Pull-down Current	Test Circuit 4, $V_{bias} = 5V$, $R = 0.1\Omega$		-2		А
	Pull-down Rds_on	$I_{GND} = I_{LG} = 0.7A$		0.65		Ω
t ₈	Rise Time	Timing Diagram, C _{LOAD} =		18		ns
t ₂	Fall Time	3.3nF		6		ns
t ₇	Pull-up Dead Time	Timing Diagram		28		ns
t ₁	Pull-down Delay	Timing Diagram, from PWM_IN Rising Edge		15		ns
LOGIC	•	•	•	•	•	•
V_{uvlo_up}	Power On Threshold	VCC rises from 0V toward 5V		3.0		V
V_{uvlo_dn}	Under-Voltage-Lock-Out Threshold			2.5		V
V_{uvlo_hys}	Under-Voltage-Lock-Out Hysteresis			0.5		V

3 www.national.com

Electrical Characteristics

LM2725 (Continued)

VCC = CBOOT = 5V, SW = GND = 0V, unless otherwise specified. Typicals and limits appearing in plain type apply for $T_A = T_J = +25^{\circ}C$. Limits appearing in **boldface** type apply over the entire operating temperature range.

Symbol	Parameter	Condition	Min	Тур	Max	Units
LOGIC	•				•	
V _{IH_EN}	EN Pin High Input		2.4			V
V _{IL_EN}	EN Pin Low Input				0.8	V
I _{leak_EN}	EN Pin Leakage Current	EN = VCC = 5V	-2		2	
		VCC = 5V, EN = 0V	-2		2	μA
t _{on_min}	Minimum Positive Input Pulse Width (Note 4)			55		
t _{off_min}	Minimum Negative Input Pulse Width (Note 5)			55		- ns
V _{IH_PWM}	PWM_IN High Level Input Voltage	When PWM_IN pin goes high from 0V	2.4			V
V _{IL_PWM}	PWM_IN Low Level Input Voltage	When PWM_IN pin goes low from 5V			0.8]

Electrical Characteristics LM2726

VCC = CBOOT = 5V, SW = GND = 0V, unless otherwise specified. Typicals and limits appearing in plain type apply for $T_A = T_J = +25^{\circ}C$. Limits appearing in **boldface** type apply over the entire operating temperature range.

Symbol	Parameter	Condition	Min	Тур	Max	Unit
POWER SUPI	PLY				•	•
I _{q_op}	Operating Quiescent Current	PWM_IN = 0V		185	250	μA
I _{q_sd}	Shutdown Quiescent Current	EN = 0V, PWM_IN = 0V		0.5	15	μA
TOP DRIVER				•	•	•
	Peak Pull-Up Current	Test Circuit 1, $V_{bias} = 5V$, $R = 0.1\Omega$		3.0		А
	Pull-Up Rds_on	$I_{CBOOT} = I_{HG} = 1.0A$		1.2		Ω
	Peak Pull-down Current	Test Circuit 2, $V_{bias} = 5V$, $R = 0.1\Omega$		-3.2		А
	Pull-down Rds_on	$I_{SW} = I_{HG} = 1.0A$		0.5		Ω
t ₄	Rise Time	Timing Diagram, C _{LOAD} =		17		ns
t ₆	Fall Time	3.3nF		12		ns
t ₃	Pull-Up Dead Time	Timing Diagram		19		ns
t ₅	Pull-Down Delay	Timing Diagram, from PWM_IN from Falling Edge		27		ns
BOTTOM DRI	VER					•
	Peak Pull-Up Current	Test Circuit 3, $V_{bias} = 5V$, $R = 0.1\Omega$		3.2		А
	Pull-up Rds_on	$I_{VCC} = I_{LG} = 1.0A$		1.1		Ω
	Peak Pull-down Current	Test Circuit 4, $V_{bias} = 5V$, $R = 0.1\Omega$		-3.2		А
	Pull-down Rds_on	$I_{GND} = I_{LG} = 1.0A$		0.6		Ω
t ₈	Rise Time	Timing Diagram, C _{LOAD} =		17		ns
t ₂	Fall Time	3.3nF		14		ns
t ₇	Pull-up Dead Time	Timing Diagram		12		ns

Electrical Characteristics LM2726 (Continued)

VCC = CBOOT = 5V, SW = GND = 0V, unless otherwise specified. Typicals and limits appearing in plain type apply for $T_A = T_J = +25^{\circ}C$. Limits appearing in **boldface** type apply over the entire operating temperature range.

Symbol	Parameter	Condition	Min	Тур	Max	Units
BOTTOM DRI	VER			•	•	•
t ₁	Pull-down Delay	Timing Diagram, from PWM_IN Rising Edge		13		ns
LOGIC				•	•	•
V _{uvlo_up}	Power On Threshold	VCC rises from 0V toward 5V		2.8		V
V_{uvlo_dn}	Under-Voltage-Lock-Out Threshold			2.5		V
V _{uvlo_hys}	Under-Voltage-Lock-Out Hysteresis			0.3		V
V _{IH_EN}	EN Pin High Input		2.4			V
$V_{IL_{EN}}$	EN Pin Low Input				0.25	V
I _{leak_EN}	EN Pin Leakage Current	EN = VCC = 5V	-2		2	μΑ
		VCC = 5V, EN = 0V	-2		2	_ μA
t _{on_min}	Minimum Positive Input Pulse Width (Note 4)			55		
t _{off_min}	Minimum Negative Input Pulse Width (Note 5)			55		- ns
V_{IH_PWM}	PWM_IN High Level Input Voltage	When PWM_IN pin goes high from 0V	2.4			.,
V_{IL_PWM}	PWM_IN Low Level Input Voltage	When PWM_IN pin goes low from 5V			0.25	V

Note 1: Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating ratings are conditions under which the device operates correctly. Operating Ratings do not imply guaranteed performance limits.

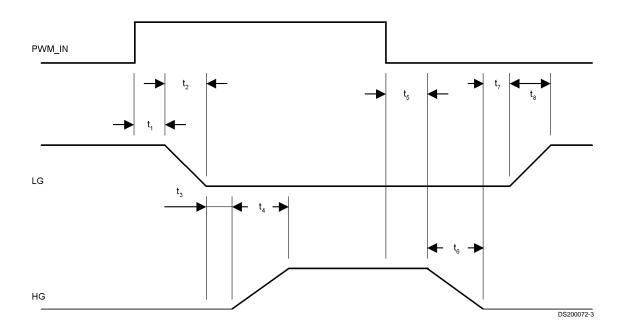
Note 2: Maximum allowable power dissipation is a function of the maximum junction temperature, T_{JMAX} , the junction-to-ambient thermal resistance, θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation at any ambient temperature is calculated using: $P_{MAX} = (T_{JMAX} - T_A) / \theta_{JA}$. The junction-to-ambient thermal resistance, θ_{JA} , for LM2725/LM2726 is 172°C/W. For a T_{JMAX} of 150°C and T_A of 25°C, the maximum allowable power dissipation is 0.7W.

Note 3: ESD machine model susceptibility is 100V.

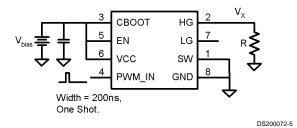
Note 4: If after a rising edge, a falling edge occurs sooner than the specified value, the IC may intermittently fail to turn on the bottom gate when the top gate is off. As the falling edge occurs sooner and sooner, the driver may start to ignore the pulse and produce no output.

Note 5: If after a falling edge, a rising edge occurs sooner than the specified value, the IC may intermittently fail to turn on the top gate when the bottom gate is off. As the rising edge occurs sooner and sooner, the driver may start to ignore the pulse and produce no output.

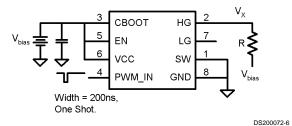
Timing Diagram



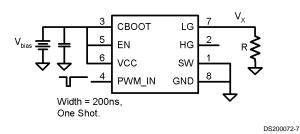
Test Circuits



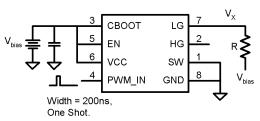
Test Circuit 1



Test Circuit 2



Test Circuit 3



DS200072-8

$$I_{\text{pull_down}} = \frac{V_{\text{bias}} - V_{x}}{R}$$

$$R_{ds_pull_up} = \frac{V_{bias} - V_x}{V_v} \cdot R$$

$$R_{ds_pull_up} = \frac{V_x}{V_{bias} - V_x} . R$$

Typical Waveforms

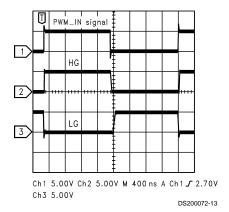


FIGURE 1. Switching Waveforms of Test Circuit

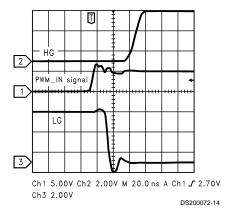


FIGURE 2. When Input Goes High

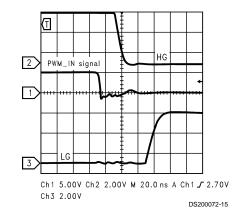


FIGURE 3. When Input Goes Low

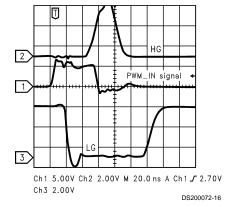
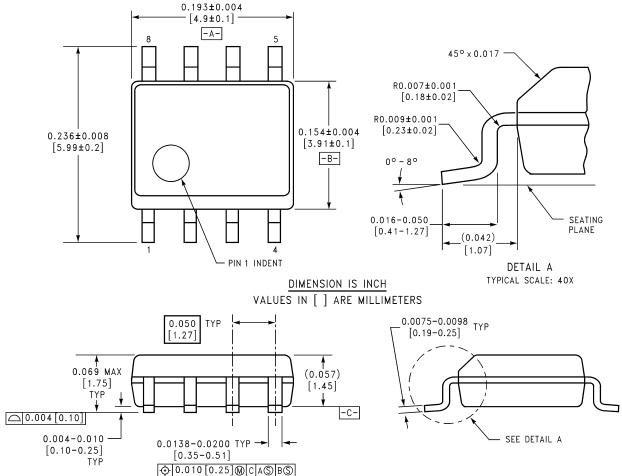


FIGURE 4. Minimum Positive Pulse

Physical Dimensions inches (millimeters) unless otherwise noted



8-Lead Small Outline Package NS Package Number M08A

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.



National Semiconductor Corporation

Americas Tel: 1-800-272-9959 Fax: 1-800-737-7018 Email: support@nsc.com

www.national.com

National Semiconductor

Europe

Fax: +49 (0) 180-530 85 86 Email: europe.support@nsc.com Deutsch Tel: +49 (0) 69 9508 6208 English Tel: +44 (0) 870 24 0 2171

English Tel: +44 (0) 870 24 0 217 Français Tel: +33 (0) 1 41 91 8790 National Semiconductor Asia Pacific Customer Response Group Tel: 65-2544466

Fax: 65-2504466 Email: ap.support@nsc.com National Semiconductor Japan Ltd. Tel: 81-3-5639-7560

Tel: 81-3-5639-7560 Fax: 81-3-5639-7507

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.